

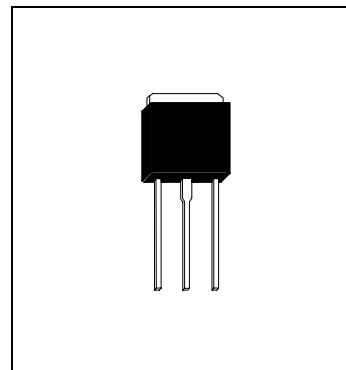


HI3055

NPN EPITAXIAL PLANAR TRANSISTOR

Description

The HI3055 is designed for general purpose of amplifier and switching applications.



Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
 - Storage Temperature -55 ~ +150 °C
 - Junction Temperature +150 °C
- Maximum Power Dissipation
 - Total Power Dissipation (Tc=25°C) 20W
- Maximum Voltages and Currents
 - BVCBO Collector to Base Voltage 70 V
 - BVCEO Collector to Emitter Voltage 60 V
 - BVEBO Emitter to Base Voltage 5 V
 - IC Collector Current 10 A
 - IB Base Current 6 A

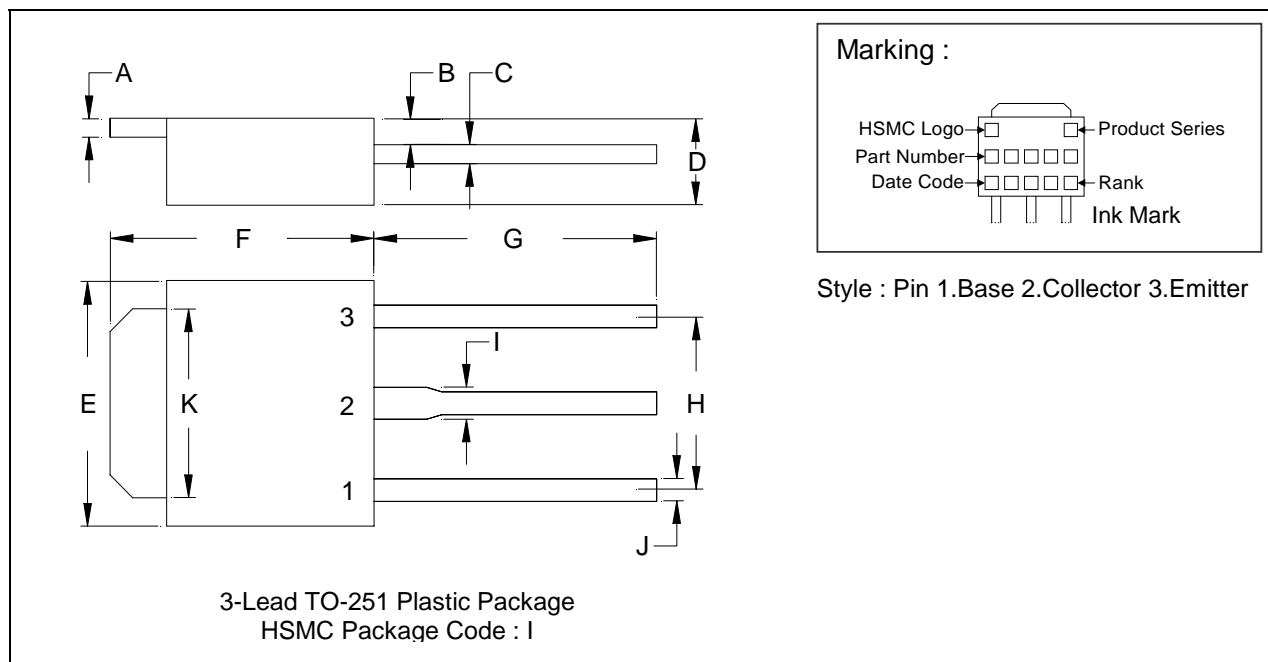
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	70	-	-	V	IC=200mA, IE=0
BVCEO	60	-	-	V	IC=10mA, IB=0
BVEBO	5	-	-	V	IE=10mA, IC=0
ICBO	-	-	20	uA	VCB=70V, IE=0
ICEX	-	-	20	uA	VCE=70V, VEB(off)=1.5V
ICEO	-	-	50	uA	VCE=30V, IB=0
IEBO	-	-	0.5	mA	VEB=5V, IC=0
*VCE(sat)1	-	-	1.1	V	IC=4A, IB=400mA
*VCE(sat)2	-	-	8	V	IC=10A, IB=3.3A
*VBE(on)	-	-	1.8	V	VCE=4V, IC=4A
*hFE1	20	-	100		VCE=4V, IC=4A
*hFE2	5	-	-		VCE=4V, IC=10A
fT	2	-	-	MHz	VCE=10V, IC=500mA, f=1MHz

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%



TO-251 Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0177	0.0217	0.45	0.55	G	0.2559	-	6.50	-
B	0.0354	0.0591	0.90	1.50	H	-	*0.1811	-	*4.60
C	0.0177	0.0236	0.45	0.60	I	-	0.0354	-	0.90
D	0.0866	0.0945	2.20	2.40	J	-	0.0315	-	0.80
E	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2677	0.2835	6.80	7.20					

- Notes :**
- 1.Dimension and tolerance based on our Spec. dated May. 24,1995.
 - 2.Controlling dimension : millimeters.
 - 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 - 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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Head Office And Factory :

- **Head Office** (Hi-Sincerity Microelectronics Corp.) : 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
Tel : 886-2-25212056 Fax : 886-2-25632712, 25368454
- **Factory 1** : No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
Tel : 886-3-5983621~5 Fax : 886-3-5982931